Lattice Semiconductor Corporation - LFSCM3GA115EP1-6FFN1704I Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

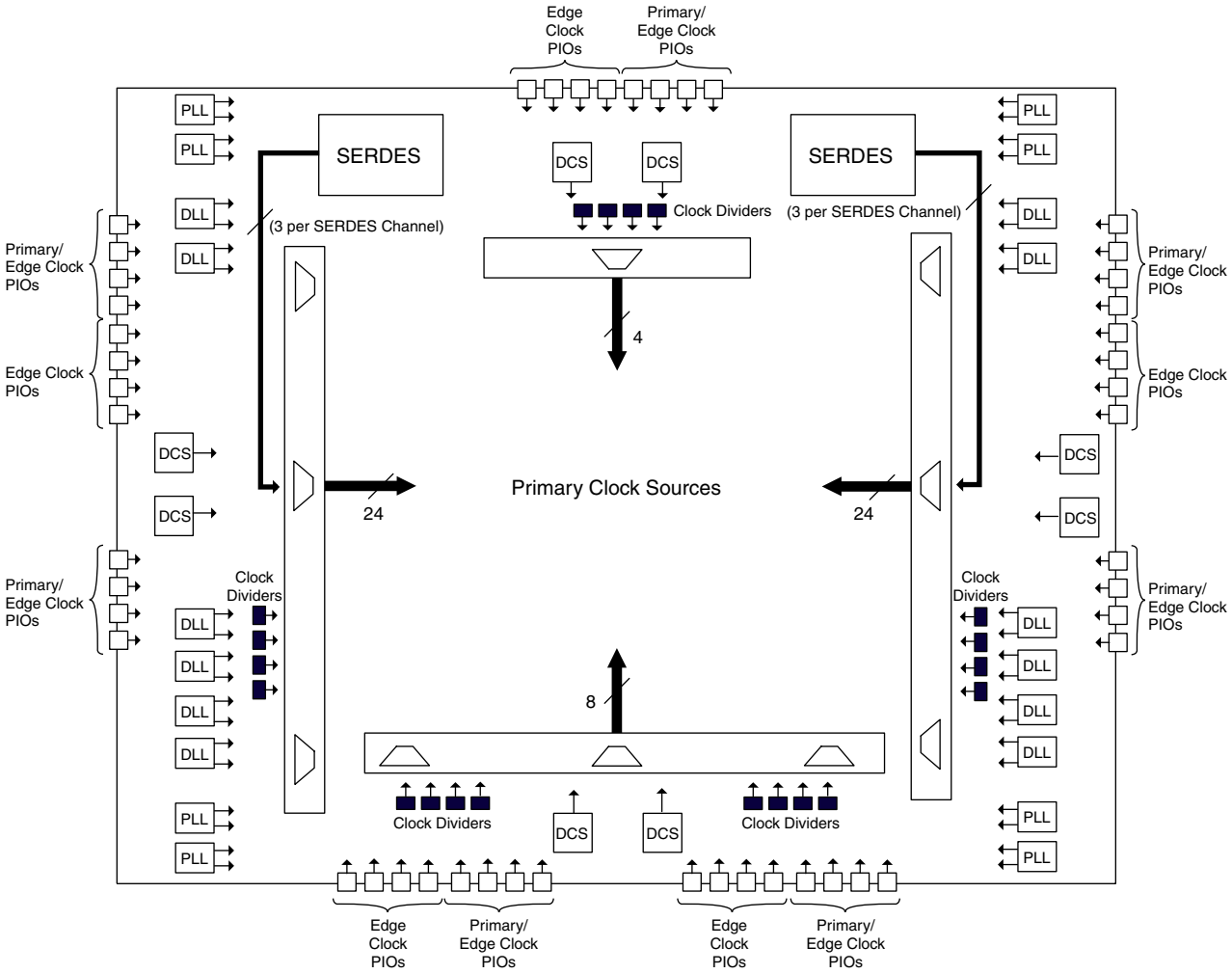
The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	28750
Number of Logic Elements/Cells	115000
Total RAM Bits	7987200
Number of I/O	942
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	1704-BBGA, FCBGA
Supplier Device Package	1704-OFCBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga115ep1-6ffn1704i

- Two outputs per PLL
- Clock divider outputs
- Digital Clock Select (DCS) block outputs
- Three outputs per SERDES quad

Figure 2-5 shows the arrangement of the primary clock sources.

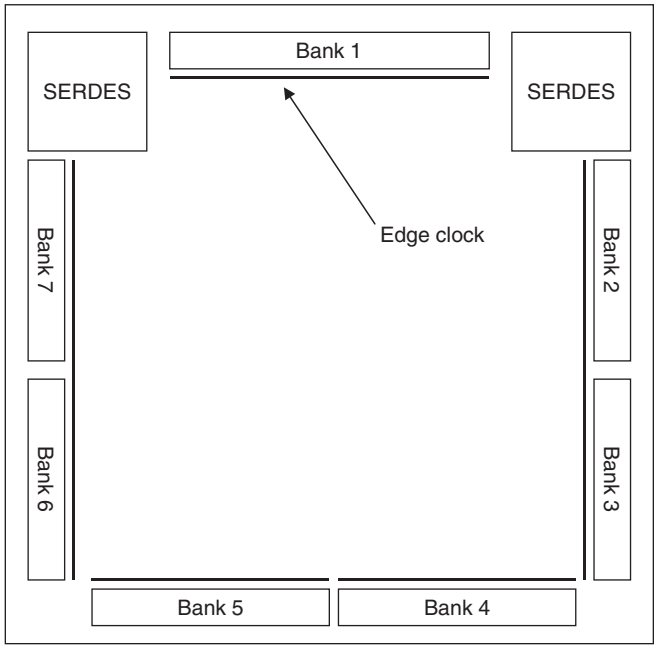
Figure 2-5. Clock Sources



Primary Clock Routing

The clock routing structure in LatticeSC devices consists of 12 Primary Clock lines per quadrant. The primary clocks are generated from 64:1 MUXs located in each quadrant. Three of the inputs to each 64:1 MUX comes from local routing, one is connected to GND and rest of the 60 inputs are from the primary clock sources. Figure 2-6 shows this clock routing.

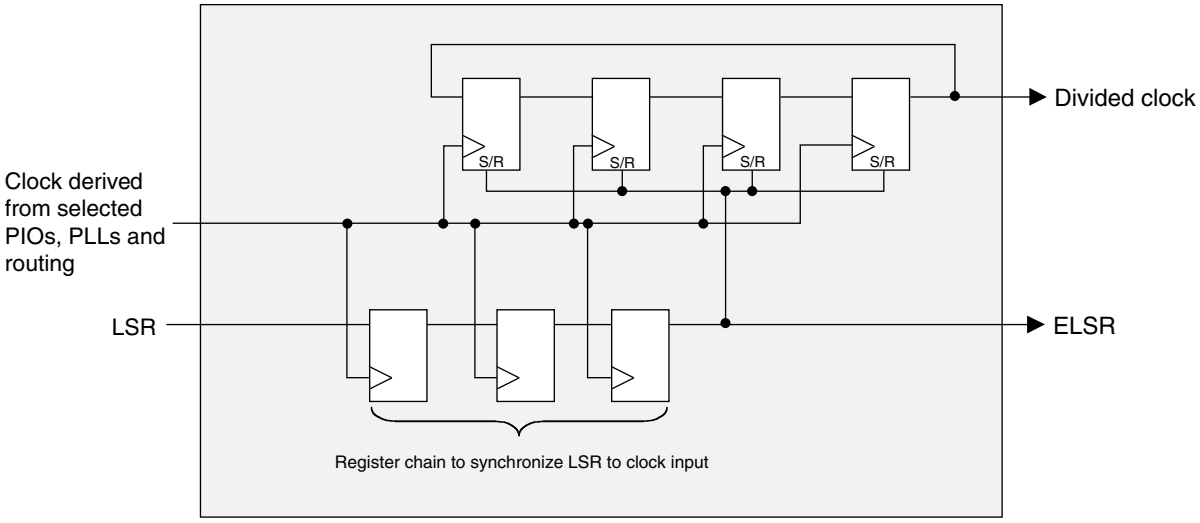
Figure 2-7. Edge Clock Resources



Precision Clock Divider

Each set of edge clocks has four high-speed dividers associated with it. These are intended for generating a slower speed system clock from the high-speed edge clock. The block operates in a DIV2 or DIV4 mode and maintains a known phase relationship between the divided down clock and high-speed clock based on the release of its reset signal. The clock dividers can be fed from selected PIOs, PLLs and routing. The clock divider outputs serve as primary clock sources. This circuit also generates an edge local set/reset (ELSR) signal which is fed to the PIOs via the edge clock network and is used for the rest of the I/O gearing logic.

Figure 2-8. Clock Divider Circuit



Dynamic Clock Select (DCS)

The DCS is a global clock buffer with smart multiplexer functions. It takes two independent input clock sources and outputs a clock signal without any glitches or runt pulses. This is achieved irrespective of where the select signal is

Figure 2-26. LatticeSC Banks

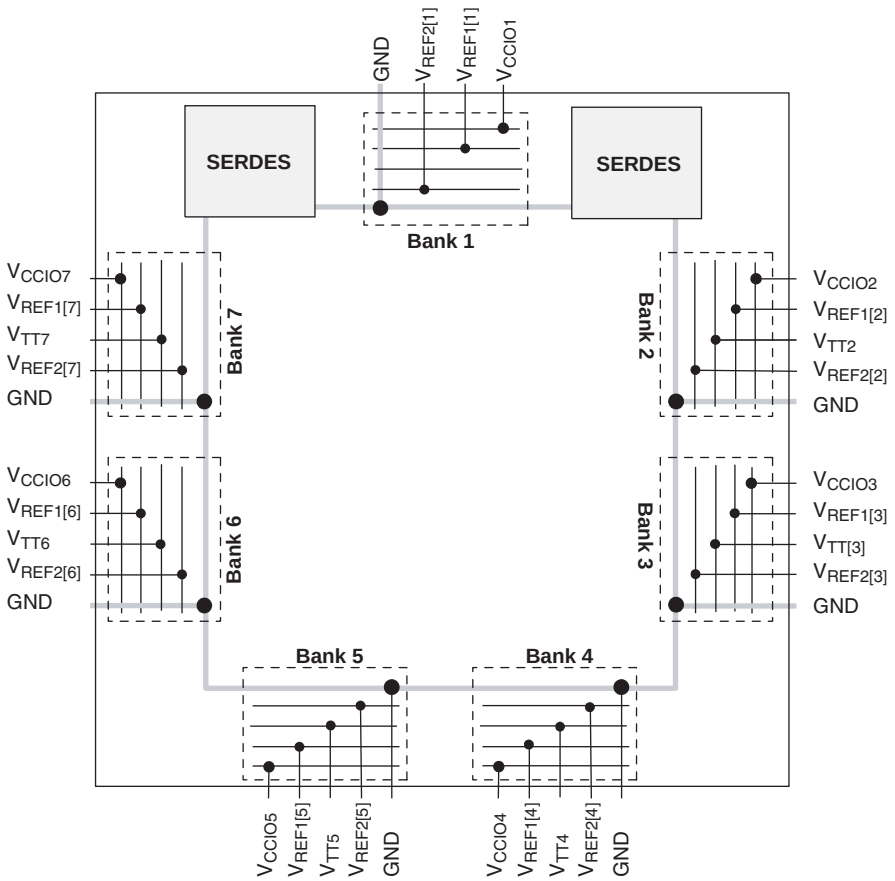


Table 2-7. Maximum Number of I/Os Per Bank in LatticeSC Family

Device	LFSC/M15	LFSC/M25	LFSC/M40	LFSC/M80	LFSC/M115
Bank1	104	80	136	80	136
Bank2	28	36	60	96	136
Bank3	60	84	96	132	156
Bank4	72	100	124	184	208
Bank5	72	100	124	184	208
Bank6	60	84	96	132	156
Bank7	28	36	60	96	136

Note: Not all the I/Os of the Banks are available in all the packages

The LatticeSC devices contain three types of PURESPEED I/O buffers:

1. **Left and Right Sides (Banks 2, 3, 6 and 7)**
   These buffers can support LVCMOS standards up to 2.5V. A differential output driver (for LVDS and RSDS) is provided on all primary PIO pairs (A and B) and differential receivers are available on all pairs. Complimentary drivers are available. Adaptive input logic is available on PIOs A or C.

2. **Top Side (Bank 1)**
   These buffers can support LVCMOS standards up to 3.3V, including PCI33, PCI-X33 and SSTL-33. Differential receivers are provided on all PIO pairs but differential drivers for LVDS and RSDS are not available. Adaptive input logic is not available on this side. Complimentary output drivers are available.

3. **Bottom Side (Banks 4 and 5)**
   These buffers can support LVCMOS standards up to 3.3V, including PCI33, PCI-X33 and SSTL-33. Differential receivers are provided on all PIO pairs but true HLVDS and RSDS differential drivers are not available. Adaptive input logic is available on PIOs A or C.

Table 2-8 lists the standards supported by each side.

Table 2-8. I/O Standards Supported by Different Banks

Description	Top Side Banks 1	Right Side Banks 2-3	Bottom Side Banks 4-5	Left Side Banks 6-7
I/O Buffer Type	Single-ended, Differential Receiver	Single-ended, Differential Receiver and Driver	Single-ended, Differential Receiver	Single-ended, Differential Receiver and Driver
Output Standards Supported	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II SSTL33_ I, II HSTL15_I, II, III[1], IV[1] HSTL18_I, II,III[1], IV[1] SSTL18D_I, II SSTL25D_I, II SSTL33D_I, II HSTL15D_I, II HSTL18D_I, II PCI33 PCIX15 PCIX33 AGP1X33 AGP2X33 MLVDS/BLVDS GTL[2], GTL+[2]	LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II HSTL15_I,III HSTL18_I,II,III PCIX15 SSTL18D_I, II SSTL25D_I, II HSTL15D_I, II HSTL18D_I, II LVDS/RSDS Mini-LVDS MLVDS/BLVDS GTL[2], GTL+[2]	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II SSTL33_ I, II HSTL15_I, II, III[1], IV[1] HSTL18_I, II,III[1], IV[1] SSTL18D_I, II SSTL25D_I, II SSTL33D_I, II HSTL15D_I, II HSTL18D_I, II PCI33 PCIX15 PCIX33 AGP1X33 AGP2X33 MLVDS/BLVDS GTL[2], GTL+[2]	LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II HSTL15_I,III HSTL18_I,II,III PCIX15 SSTL18D_I, II SSTL25D_I, II HSTL15D_I, II HSTL18D_I, II LVDS/RSDS Mini-LVDS MLVDS/BLVDS GTL[2], GTL+[2]
Input Standards Supported	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential
Clock Inputs	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential
Differential Output Support via Emulation	LVDS/MLVDS/BLVDS/ LVPECL	MLVDS/BLVDS/ LVPECL	LVDS/MLVDS/BLVDS/ LVPECL	MLVDS/BLVDS/ LVPECL
AIL Support	No	Yes	Yes	Yes

1. Input only.
2. Input only. Outputs supported by bussing multiple outputs together.

Supported Standards

The LatticeSC PURESPEED I/O buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 12, 15, 18, 25 and 33 standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, termination resistance, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL, HSTL, GTL (input only), GTL+ (input only), PCI33, PCIX33, PCIX15, AGP-1X33 and AGP-2X33. Differential standards supported include LVDS, RSDS, BLVDS, MLVDS, LVPECL, differential SSTL and differential HSTL. Tables 12 and 13 show the I/O standards (together with their supply and reference voltages) supported by the LatticeSC devices. The tables also provide the available internal termination schemes. For further information on utilizing the PURESPEED I/O buffer to support a variety of standards please see details of additional technical documentation at the end of this data sheet.

Table 2-9. Supported Input Standards

Input Standard	V_{REF} (Nom.)	V_{CCIO}[1] (Nom.)	On-chip Termination
Single Ended Interfaces			
LVTTL33[3]	—	3.3	None
LVCMOS 33, 25, 18, 15, 12[3]	—	3.3/2.5/1.8/1.5/1.2	None
PCI33, PCIX33, AGP1X33[3]	—	3.3	None
PCIX15	0.75	1.5[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
AGP2X33	1.32	—	None
HSTL18_I, II	0.9	1.8[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
HSTL18_III, IV	1.08	1.8[2]	None / V_{CCIO}: 50
HSTL15_I, II	0.75	1.5[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
HSTL15_III, IV	0.9	1.5[2]	None / V_{CCIO}: 50
SSTL33_I, II	1.5	3.3	None
SSTL25_I, II	1.25	2.5[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
SSTL18_I, II	0.9	1.8[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
GTL+, GTL	1.0 / 0.8	1.5 / 1.2[2]	None / V_{CCIO}: 50
Differential Interfaces			
SSTL18D_I, II	—	1.8[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
SSTL25D_I, II	—	2.5[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
SSTL33D_I, II	—	3.3	None
HSTL15D_I, II	—	1.5[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
HSTL18D_I, II	—	1.8[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
LVDS	—	—	None / Diff: 120, 150, 220, 240/ Diff to V_{CMT}: 120, 150, 220, 240
Mini-LVDS	—	—	None / Diff: 120, 150 / Diff to V_{CMT}: 120, 150
BLVDS25	—	—	None
MLVDS25	—	—	None
RSDS	—	—	None / Diff: 120, 150, 220, 240/ Diff to V_{CMT}: 120, 150, 220, 240
LVPECL33	—	≤2.5	None / Diff: 120, 150, 220, 240/ Diff to V_{CMT}: 120, 150, 220, 240

1. When not specified V_{CCIO} can be set anywhere in the valid operating range.
2. V_{CCIO} needed for on-chip termination to $V_{CCIO}/2$ or V_{CCIO} only. V_{CCIO} is not specified for off-chip termination or V_{TT} termination.
3. All ratioed input buffers and dedicated pin input buffers include hysteresis with a typical value of 50mV.

VDDAX25 needs to be connected independent of the use of the SERDES. This supply is used to control the SERDES CML I/O regardless of the SERDES being used in the design.

Supported Source Synchronous Interfaces

The LatticeSC devices contain a variety of hardware, such as delay elements, DDR registers and PLLs, to simplify the implementation of Source Synchronous interfaces. Table 2-11 lists Source Synchronous and DDR/QDR standards supported in the LatticeSC. For additional detail refer to technical information at the end of the data sheet.

Table 2-11. Source Synchronous Standards Table[1]

Source Synchronous Standard	Clocking	Speeds (MHz)	Data Rate (Mbps)
RapidIO	DDR	500	1000
SPI4.2 (POS-PHY4)/NPSI	DDR	500	1000
SFI4/XSBI	DDR SDR	334 667	667
XGMII	DDR	156.25	312
CSIX	SDR	250	250
QDRII/QDRII+ memory interface	DDR	300	600
DDR memory interface	DDR	240	480
DDRII memory interface	DDR	333	667
RLDRAM memory interface	DDR	400	800

1. Memory width is dependent on the system design and limited by the number of I/Os in the device.

flexiPCS™ (Physical Coding Sublayer Block)

flexiPCS Functionality

The LatticeSC family combines a high-performance FPGA fabric, high-performance I/Os and large embedded RAM in a single industry leading architecture. LatticeSC devices also feature up to 32 channels of embedded SERDES with associated Physical Coding Sublayer (PCS) logic. The flexiPCS logic can be configured to support numerous industry standard high-speed data transfer protocols.

Each channel of flexiPCS logic contains dedicated transmit and receive SERDES for high-speed, full-duplex serial data transfers at data rates up to 3.8 Gbps. The PCS logic in each channel can be configured to support an array of popular data protocols including SONET (STS-12/STS-12c, STS-48/STS-48c, and TFI-5 support of 10 Gbps or above), Gigabit Ethernet (compliant to the IEEE 1000BASE-X specification), 1.02 or 2.04 Gbps Fibre Channel, PCI-Express, and Serial RapidIO. In addition, the protocol based logic can be fully or partially bypassed in a number of configurations to allow users flexibility in designing their own high-speed data interface.

Protocols requiring data rates above 3.8 Gbps can be accommodated by dedicating either one pair or all four channels in one flexiPCS quad block to one data link. One quad can support full-duplex serial data transfers at data rates up to 15.2 Gbps. A single flexiPCS quad can be configured to support 10Gb Ethernet (with a fully compliant XAUI interface), 10Gb Fibre Channel, and x4 PCI-Express and 4x RapidIO.

The flexiPCS also provides bypass modes that allow a direct 8-bit or 10-bit interface from the SERDES to the FPGA logic which can also be geared to run at 1/2 speed for a 16-bit or 20-bit interface to the FPGA logic. Each SERDES pin can be DC coupled independently and can allow for both high-speed and low-speed operation down to DC rates on the same SERDES pin, as required by some Serial Digital Video applications.

The ispLEVER design tools from Lattice support all modes of the flexiPCS. Most modes are dedicated to applications associated with a specific industry standard data protocol. Other more general purpose modes allow a user to define their own operation. With ispLEVER, the user can define the mode for each quad in a design. Nine modes are currently supported by the ispLEVER design flow:

RSDS

Over Recommended Operating Conditions

Parameter Symbol	Description	Min.	Typ.	Max.	Units
V_{OD}	Output voltage, differential, R_T = 100 ohms	100	200	600	mV
V_{OS}	Output voltage, common mode	0.5	1.2	1.5	V
I_{RSDS}	Differential driver output current	1	2	6	mA
V_{THD}	Input voltage differential	100	—	—	mV
V_{CM}	Input common mode voltage	0.3	—	1.5	V
T_R, T_F	Output rise and fall times, 20% to 80%	—	500	—	ps
T_{ODUTY}	Output clock duty cycle	45	50	55	%

Note: Data is for 2mA drive. Other differential driver current options are available.

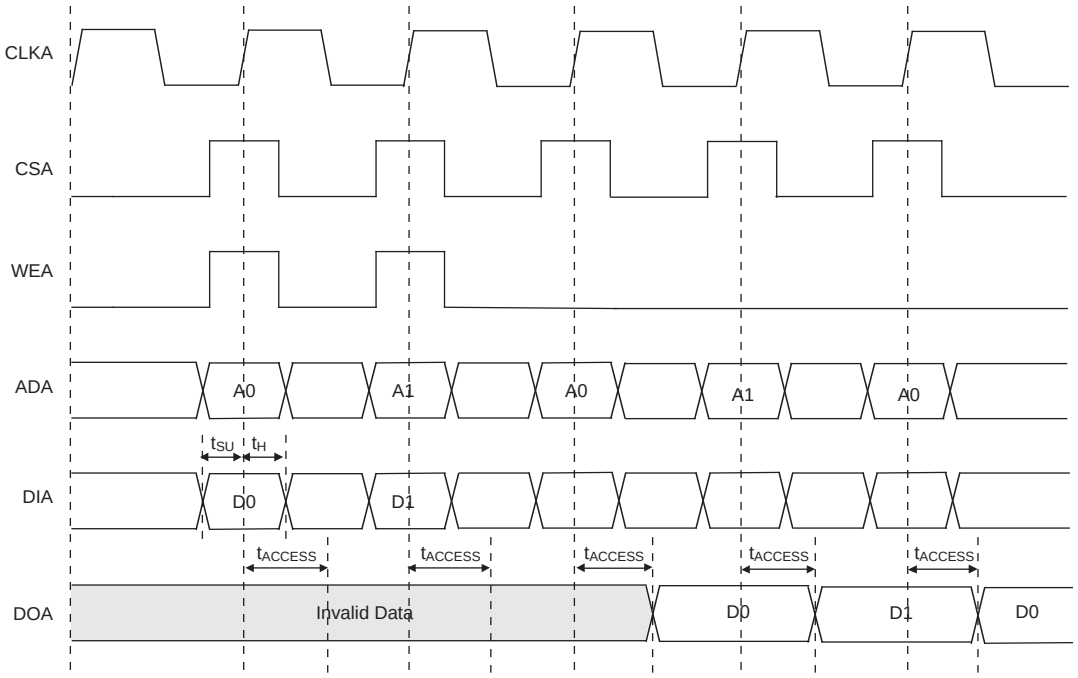
LatticeSC/M Family Timing Adders (Continued)

Over Recommended Operating Conditions at VCC = 1.2V +/- 5%

Buffer Type	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
LVCMOS18_12mA	LVCMOS 1.8 12mA drive	0.024	-0.106	0.019	-0.004	0.016	0.099	ns
LVCMOS18_16mA	LVCMOS 1.8 16mA drive	0.074	-0.134	0.08	-0.022	0.088	0.089	ns
LVCMOS18_OD	LVCMOS 1.8 open drain	0.002	-0.206	0	-0.196	-0.002	-0.221	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive	-0.344	-0.164	-0.379	-0.186	-0.412	-0.209	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive	-0.125	-0.137	-0.145	-0.157	-0.164	-0.176	ns
LVCMOS15_12mA	LVCMOS 1.5 12mA drive	-0.027	-0.166	-0.043	-0.07	-0.059	0.026	ns
LVCMOS15_16mA	LVCMOS 1.5 16mA drive	0.025	-0.195	0.013	-0.089	0.003	0.017	ns
LVCMOS15_OD	LVCMOS 1.5 open drain	-0.047	-0.267	-0.067	-0.267	-0.087	-0.299	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive	-0.473	-0.293	-0.505	-0.317	-0.537	-0.34	ns
LVCMOS12_4mA	LVCMOS 1.2 4mA drive	-0.218	-0.239	-0.25	-0.271	-0.28	-0.303	ns
LVCMOS12_8mA	LVCMOS 1.2 8mA drive	-0.109	-0.269	-0.143	-0.181	-0.176	-0.093	ns
LVCMOS12_12mA	LVCMOS 1.2 12mA drive	-0.054	-0.3	-0.085	-0.203	-0.114	-0.106	ns
LVCMOS12_OD	LVCMOS 1.2 open drain	-0.126	-0.371	-0.166	-0.398	-0.204	-0.43	ns
PCI33	PCI	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns
PCIX33	PCI-X 3.3	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns
PCIX15	PCI-X 1.5	0.208	0.227	0.233	0.312	0.259	0.398	ns
AGP1X33	AGP-1X 3.3	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns
AGP2X33	AGP-2X	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns

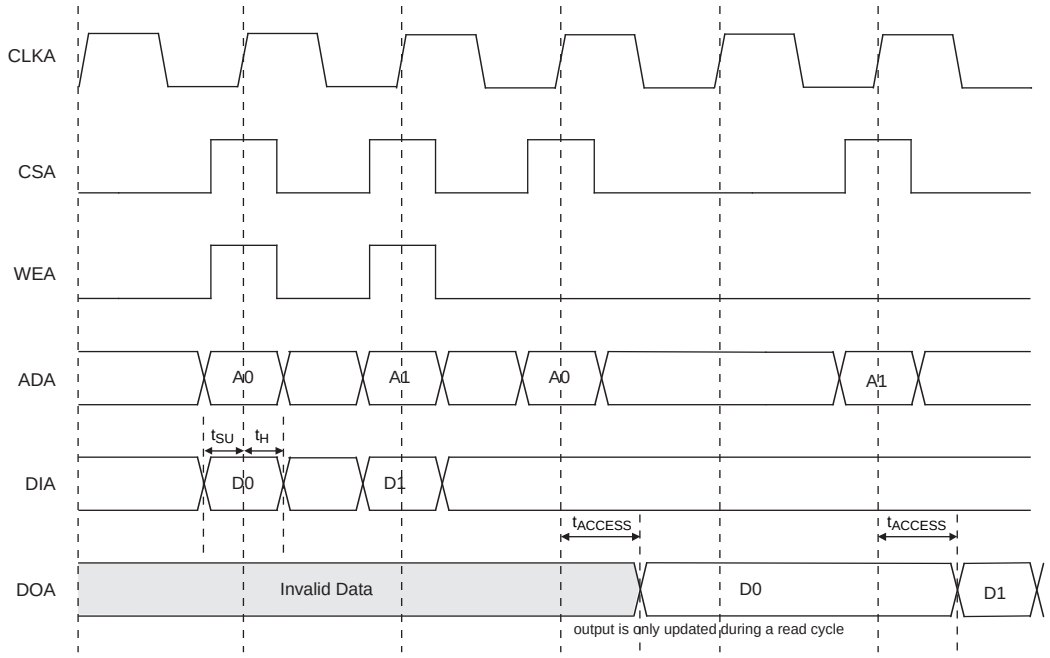
EBR Memory Timing Diagrams

Figure 3-6. Read Mode



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

Figure 3-7. Read Mode with Input Registers Only



sysCLOCK DLL Timing

Over Recommended Operating Conditions

Parameter	Description	Conditions	Min.	Typ.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		100	—	700	MHz
f_{OUTOP}	Output Clock Frequency (CLKOP)		100	—	700	MHz
f_{OUTOS}	Output Clock Frequency (CLKOS)		25	—	700	MHz
AC Characteristics						
t_{DUTY}	Output Clock Duty Cycle	Output Clock Duty Cycle (at 50% levels, 50% duty cycle input clock, duty cycle correction turned off, time reference delay mode)	38	—	62	%
t_{DUTYRD}	Output Clock Duty Cycle	Output Clock Duty Cycle (at 50% levels, arbitrary duty cycle input clock, duty cycle correction turned on, time reference delay mode)	45	—	55	%
$t_{DUTYCIR}$	Output Clock Duty Cycle	Output Clock Duty Cycle (at 50% levels, arbitrary duty cycle input clock, duty cycle correction turned on, clock injection removal mode)	40	—	60	%
t_{OPJIT}[1]	Output Clock Period Jitter		—	—	200	ps
t_{CPJIT}[1]	Output Clock Cycle-to-Cycle Jitter		—	—	200	ps
t_{SKEW}	Output Clock to Clock Skew (Between Two Outputs with the Same Phase Setting)		—	—	100	ps
t_{LOCK}	DLL Lock-in Time		8	—	18500	cycles
t_{IDUTY}	Input Clock Duty Cycle	Applies to all operating conditions	35	—	65	%
t_{IPJIT}	Input Clock Period Jitter		—	—	+/- 250	ps
t_{HI}	Input Clock High Time	At 80% level	500	—	—	ps
t_{LO}	Input Clock Low Time	At 20% level	500	—	—	ps
t_{RSWD}	Reset Signal Pulse Width		3	—	—	ns
t_{FDEL}	Timeshift Delay Step Size		35	45	80	ps
t_{DLL}	Delay Through the DLL when No Delay Taps are Chosen but Not in Bypass Mode.		—	760	—	ps

1. Values are measured with FPGA logic active, no additional I/Os toggling and REFCLK total jitter = 30 ps.

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
W7	GND	-		GND	-	
AA14	VCC	-		VCC	-	
AA16	VCC	-		VCC	-	
AA17	VCC	-		VCC	-	
AA18	VCC	-		VCC	-	
AA19	VCC	-		VCC	-	
AA21	VCC	-		VCC	-	
AB13	VCC	-		VCC	-	
AB22	VCC	-		VCC	-	
N13	VCC	-		VCC	-	
N22	VCC	-		VCC	-	
P14	VCC	-		VCC	-	
P16	VCC	-		VCC	-	
P17	VCC	-		VCC	-	
P18	VCC	-		VCC	-	
P19	VCC	-		VCC	-	
P21	VCC	-		VCC	-	
R15	VCC	-		VCC	-	
R17	VCC	-		VCC	-	
R18	VCC	-		VCC	-	
R20	VCC	-		VCC	-	
T14	VCC	-		VCC	-	
T16	VCC	-		VCC	-	
T19	VCC	-		VCC	-	
T21	VCC	-		VCC	-	
U14	VCC	-		VCC	-	
U15	VCC	-		VCC	-	
U17	VCC	-		VCC	-	
U18	VCC	-		VCC	-	
U20	VCC	-		VCC	-	
U21	VCC	-		VCC	-	
V14	VCC	-		VCC	-	
V15	VCC	-		VCC	-	
V17	VCC	-		VCC	-	
V18	VCC	-		VCC	-	
V20	VCC	-		VCC	-	
V21	VCC	-		VCC	-	
W14	VCC	-		VCC	-	
W16	VCC	-		VCC	-	
W19	VCC	-		VCC	-	
W21	VCC	-		VCC	-	
Y15	VCC	-		VCC	-	
Y17	VCC	-		VCC	-	
Y18	VCC	-		VCC	-	
Y20	VCC	-		VCC	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
W13	VCCAUX	-		VCCAUX	-	
W22	VCCAUX	-		VCCAUX	-	
Y21	GND	-		GND	-	
Y25	GND	-		GND	-	
C18	VCCIO1	-		VCCIO1	-	
D17	VCCIO1	-		VCCIO1	-	
F16	VCCIO1	-		VCCIO1	-	
G19	VCCIO1	-		VCCIO1	-	
J20	VCCIO1	-		VCCIO1	-	
K12	VCCIO1	-		VCCIO1	-	
K15	VCCIO1	-		VCCIO1	-	
L23	VCCIO1	-		VCCIO1	-	
Y9	GND	-		GND	-	
J9	VCCIO1	-		VCCIO1	-	
E3	VCCIO2	-		VCCIO2	-	
G6	VCCIO2	-		VCCIO2	-	
H4	VCCIO2	-		VCCIO2	-	
K7	VCCIO2	-		VCCIO2	-	
L3	VCCIO2	-		VCCIO2	-	
M11	VCCIO2	-		VCCIO2	-	
N6	VCCIO2	-		VCCIO2	-	
P4	VCCIO2	-		VCCIO2	-	
R9	VCCIO2	-		VCCIO2	-	
AA3	VCCIO3	-		VCCIO3	-	
AB7	VCCIO3	-		VCCIO3	-	
AC10	VCCIO3	-		VCCIO3	-	
AD4	VCCIO3	-		VCCIO3	-	
AE6	VCCIO3	-		VCCIO3	-	
AG3	VCCIO3	-		VCCIO3	-	
AK4	VCCIO3	-		VCCIO3	-	
T7	VCCIO3	-		VCCIO3	-	
U3	VCCIO3	-		VCCIO3	-	
V4	VCCIO3	-		VCCIO3	-	
W6	VCCIO3	-		VCCIO3	-	
Y10	VCCIO3	-		VCCIO3	-	
AD12	VCCIO4	-		VCCIO4	-	
AF15	VCCIO4	-		VCCIO4	-	
AF9	VCCIO4	-		VCCIO4	-	
AH10	VCCIO4	-		VCCIO4	-	
AH16	VCCIO4	-		VCCIO4	-	
AJ13	VCCIO4	-		VCCIO4	-	
AJ7	VCCIO4	-		VCCIO4	-	
AL14	VCCIO4	-		VCCIO4	-	
AL8	VCCIO4	-		VCCIO4	-	
AM11	VCCIO4	-		VCCIO4	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
J3	PR45A	2	
M8	PR43D	2	DIFFR_2
L8	PR43C	2	VREF1_2
K4	PR43B	2	
J4	PR43A	2	
M7	PR26D	2	
L7	PR26C	2	
J5	PR26B	2	
H5	PR26A	2	
N9	PR19D	2	
P9	PR19C	2	
G3	PR19B	2	
F3	PR19A	2	
J6	PR18D	2	VREF2_2
H6	PR18C	2	
E2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
D2	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
P10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
N10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
G4	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
F4	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
J7	PR15D	2	
H7	PR15C	2	
G5	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
F5	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
C2	VCCJ	-	
M9	TDO	-	TDO
L9	TMS	-	
D1	TCK	-	
C1	TDI	-	
J8	PROGRAMN	1	
K8	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
B2	CCLK	1	
H9	RESP_URC	-	
H10	VCC12	-	
H8	A_REFCLKN_R	-	
G8	A_REFCLKP_R	-	
C3	VCC12	-	
D3	A_VDDIB0_R	-	
A3	A_HDINP0_R	-	PCS 3E0 CH 0 IN P
B3	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
E5	VCC12	-	
A4	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
F6	A_VDDOB0_R	-	
B4	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N
F7	A_VDDOB1_R	-	
B5	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N
E6	VCC12	-	
A5	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P
B6	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
A6	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
C6	VCC12	-	
D4	A_VDDIB1_R	-	
C7	VCC12	-	
D5	A_VDDIB2_R	-	
A7	A_HDINP2_R	-	PCS 3E0 CH 2 IN P
B7	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
E7	VCC12	-	
A8	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
F8	A_VDDOB2_R	-	
B8	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
F9	A_VDDOB3_R	-	
B9	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
E8	VCC12	-	
A9	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
B10	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
A10	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
C10	VCC12	-	
D6	A_VDDIB3_R	-	
G10	VCC12	-	
D7	B_VDDIB0_R	-	
E10	B_HDINP0_R	-	PCS 3E1 CH 0 IN P
F10	B_HDINN0_R	-	PCS 3E1 CH 0 IN N
K10	VCC12	-	
A11	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P
D10	B_VDDOB0_R	-	
B11	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N
D11	B_VDDOB1_R	-	
B12	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N
L10	VCC12	-	
A12	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P
F11	B_HDINN1_R	-	PCS 3E1 CH 1 IN N
E11	B_HDINP1_R	-	PCS 3E1 CH 1 IN P
G11	VCC12	-	
D8	B_VDDIB1_R	-	
G12	VCC12	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
F25	B_HDINN0_L	-	PCS 361 CH 0 IN N
E25	B_HDINP0_L	-	PCS 361 CH 0 IN P
D28	B_VDDIB0_L	-	
G25	VCC12	-	
D29	A_VDDIB3_L	-	
C25	VCC12	-	
A25	A_HDINP3_L	-	PCS 360 CH 3 IN P
B25	A_HDINN3_L	-	PCS 360 CH 3 IN N
A26	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
E27	VCC12	-	
B26	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
F26	A_VDDOB3_L	-	
B27	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
F27	A_VDDOB2_L	-	
A27	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
E28	VCC12	-	
B28	A_HDINN2_L	-	PCS 360 CH 2 IN N
A28	A_HDINP2_L	-	PCS 360 CH 2 IN P
D30	A_VDDIB2_L	-	
C28	VCC12	-	
D31	A_VDDIB1_L	-	
C29	VCC12	-	
A29	A_HDINP1_L	-	PCS 360 CH 1 IN P
B29	A_HDINN1_L	-	PCS 360 CH 1 IN N
A30	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
E29	VCC12	-	
B30	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
F28	A_VDDOB1_L	-	
B31	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
F29	A_VDDOB0_L	-	
A31	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
E30	VCC12	-	
B32	A_HDINN0_L	-	PCS 360 CH 0 IN N
A32	A_HDINP0_L	-	PCS 360 CH 0 IN P
D32	A_VDDIB0_L	-	
C32	VCC12	-	
E34	PL30A	7	
F34	PL30B	7	
F33	PL34A	7	
G33	PL34B	7	
K30	PL38A	7	
L30	PL38B	7	
G34	PL40A	7	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AC24	GND	-		GND	-	
AC26	GND	-		GND	-	
AC35	GND	-		GND	-	
AC8	GND	-		GND	-	
AD12	GND	-		GND	-	
AD16	GND	-		GND	-	
AD18	GND	-		GND	-	
AD20	GND	-		GND	-	
AD23	GND	-		GND	-	
AD25	GND	-		GND	-	
AD27	GND	-		GND	-	
AD31	GND	-		GND	-	
AE17	GND	-		GND	-	
AE19	GND	-		GND	-	
AE24	GND	-		GND	-	
AE26	GND	-		GND	-	
AE3	GND	-		GND	-	
AE39	GND	-		GND	-	
AF18	GND	-		GND	-	
AF20	GND	-		GND	-	
AF23	GND	-		GND	-	
AF25	GND	-		GND	-	
AF36	GND	-		GND	-	
AF7	GND	-		GND	-	
AG11	GND	-		GND	-	
AG16	GND	-		GND	-	
AG19	GND	-		GND	-	
AG24	GND	-		GND	-	
AG27	GND	-		GND	-	
AG32	GND	-		GND	-	
AH15	GND	-		GND	-	
AH28	GND	-		GND	-	
AH4	GND	-		GND	-	
AH40	GND	-		GND	-	
AJ35	GND	-		GND	-	
AJ8	GND	-		GND	-	
AK12	GND	-		GND	-	
AK31	GND	-		GND	-	
AL13	GND	-		GND	-	
AL19	GND	-		GND	-	
AL24	GND	-		GND	-	
AL3	GND	-		GND	-	
AL30	GND	-		GND	-	
AL39	GND	-		GND	-	
AM16	GND	-		GND	-	

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA40E-7FFN1020C[1]	-7	Lead-Free Organic fcBGA	1020	COM	40.4
LFSC3GA40E-6FFN1020C[1]	-6	Lead-Free Organic fcBGA	1020	COM	40.4
LFSC3GA40E-5FFN1020C[1]	-5	Lead-Free Organic fcBGA	1020	COM	40.4
LFSC3GA40E-7FFAN1020C	-7	Lead-Free Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-6FFAN1020C	-6	Lead-Free Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-5FFAN1020C	-5	Lead-Free Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-7FCN1152C[2]	-7	Lead-Free Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-6FCN1152C[2]	-6	Lead-Free Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-5FCN1152C[2]	-5	Lead-Free Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-7FFN1152C	-7	Lead-Free Organic fcBGA	1152	COM	40.4
LFSC3GA40E-6FFN1152C	-6	Lead-Free Organic fcBGA	1152	COM	40.4
LFSC3GA40E-5FFN1152C	-5	Lead-Free Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-7FFN1020C[1]	-7	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-6FFN1020C[1]	-6	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-5FFN1020C[1]	-5	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-7FFAN1020C	-7	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-6FFAN1020C	-6	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-5FFAN1020C	-5	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-7FCN1152C[2]	-7	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FCN1152C[2]	-6	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FCN1152C[2]	-5	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-7FFN1152C	-7	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FFN1152C	-6	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FFN1152C	-5	Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Industrial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-6FFN1020I[1]	-6	Lead-Free Organic fcBGA	1020	IND	40.4
LFSCM3GA40EP1-5FFN1020I[1]	-5	Lead-Free Organic fcBGA	1020	IND	40.4
LFSCM3GA40EP1-6FFAN1020I	-6	Lead-Free Organic fcBGA Revision 2	1020	IND	40.4
LFSCM3GA40EP1-5FFAN1020I	-5	Lead-Free Organic fcBGA Revision 2	1020	IND	40.4
LFSCM3GA40EP1-6FCN1152I[2]	-6	Lead-Free Ceramic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-5FCN1152I[2]	-5	Lead-Free Ceramic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA80E-6FCN1152I[1]	-6	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSC3GA80E-5FCN1152I[1]	-5	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSC3GA80E-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	80.1
LFSC3GA80E-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	80.1
LFSC3GA80E-6FCN1704I[1]	-6	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSC3GA80E-5FCN1704I[1]	-5	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSC3GA80E-6FFN1704I	-6	Lead-Free Organic fcBGA	1704	IND	80.1
LFSC3GA80E-5FFN1704I	-5	Lead-Free Organic fcBGA	1704	IND	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA80EP1-6FCN1152I[1]	-6	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-5FCN1152I[1]	-5	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-6FCN1704I[1]	-6	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-5FCN1704I[1]	-5	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-6FFN1704I	-6	Lead-Free Organic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-5FFN1704I	-5	Lead-Free Organic fcBGA	1704	IND	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Date	Version	Section	Change Summary
August 2006 (cont.)	01.3 (cont.)	DC and Switching Characteristics (cont.)	Updated LatticeSC Family Timing Adders with ispLEVER 6.0 SP1 results
			Updated PLL Timing Parameters based on PDE testing results
			Removed RDDATA parameter from sysCONFIG readback timing table
		Multiple	Changed TDO/RDDATA to TDO
		Pinout Information	Removed all MPI signals from SC15 256 pin package Dual Function Column
			Added note to SC15, SC25 900 pin package that the package supports a 16 bit MPI
			Added note that pin D3 in an SC15 and SC25 900 pin package should not be used for single-ended outputs
			Added note that pin D28 in an SC15 and SC25 900 pin package should not be used for single-ended outputs
			Added note to SC25 1020 pin package that the package supports a 16 bit MPI
			Added note to SC80 1152 pin package that the package supports a 32 bit MPI
			Added note to SC80 1704 pin package that the package supports a 32 bit MPI
		Ordering Information	Changed “fcBGA” for the 1020 packages to “ffBGA”
November 2006	01.4	Introduction	LatticeSC Family Selection Guide table – I/O count for SC80 device, 1704 fcBGA package changed to 904/32. I/O count for SC115 device, 1704 fcBGA package changed to 942/32.
		DC and Switching Characteristics	DC Electrical Characteristics table – Updated the initialization and standby supply current values.
			DC Electrical Characteristics table – Updated the sysCONFIG Master Parallel mode RCLK low and RCLK high time specifications.
			DC Electrical Characteristics table – Updated VCCIO values for LVPECL33 I/Os.
		Pin Information	Pin Information Summary table - Changed number of single ended user I/Os from 906 to 904 for 1704 fcBGA.
			Removed the single-ended only output restriction on pins D3 and D28 in an SC15 and SC25 900 pin package.
		Ordering Information	Ordering Information tables - Changed number of I/Os from 906 to 904 for 1704 fcBGA.
			Added ordering part numbers for LatticeSC/SCM 40K and 115K LUT devices.
			Added lead-free ordering part numbers.
		Multiple	Changed number of available SC80 I/O from 906 to 904.
			Changed number of available SC115 I/O from 944 to 942.
January 2007	01.4a	Architecture	Added EBR Asynchronous Reset section.
February 2007	01.4b	Architecture	Updated EBR Asynchronous Reset section.
March 2007	01.5	Architecture	Added EBR asynchronous reset clarification
			Clarified that differential drivers are not supported in banks 1, 4 and 5
		DC and Switching Characteristics	Added clarification for the description of the junction temperature specification in the Absolute Maximum Ratings section.
			Updated Initialization and Standby Current table.
			Updated LatticeSC External Switching Characteristics with ispLEVER 6.1 SP1 results.

Date	Version	Section	Change Summary
December 2011	02.4	DC and Switching Characteristics	Updated JTAG Port Timing Specifications table.